



AUTOMATIC TWIN SPINDLE DICING SAWS

7900 Duo

For 8" silicon and GaAs wafers



Features & Benefits

- Up to 8" x 8" products
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

Workpiece Size	Ø 8"	
Spindle	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm	
Blade Size	2" - 3"	
Y1 / Y2 Axis	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis	Air Slide	
Z1 / Z2 Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
Ø Axis	Repeatability	4 arc-sec
	Stroke	380°
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
	Dimensions	(W x D x H) mm
	Weight	900 kg

Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)

7920 Duo

Multi panel for dicing glass, saw devices and other application



Features & Benefits

- Up to 10" X 10" chuck
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

Workpiece Size	10" x 10"	
Spindle	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm	
Blade Size	2" - 3"	
Y1 / Y2 Axis	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis	Air Slide	
Z1 / Z2 Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
Ø Axis	Repeatability	4 arc-sec
	Stroke	380°
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
	Dimensions	(W x D x H) mm
	Weight	900 kg

Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)